The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive semiconductor, LED and LCD industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions; Other risks identified in our annual report for the year ended December 31st, 2010. All financial figures discussed herein are prepared pursuant to ROC GAAP on an un-audited unconsolidated basis. All audited figures will be publicly announced upon the completion of our audited process.
**Company at a Glance**

- **Address**: No. 155, Chung-Ho St., Chu-Pei, Hsinchu, 302 Taiwan, R.O.C.
- **Founded**: July 25, 1995
- **Paid-in Capital**: NTD$ 779.8M (2011.02.28-the latest)
- **No. of Employees**: 788 (2011.02.28)
- **Southern Taiwan Branch**: No. 7, Luke 1st Rd., Luzhu Shiang, Kaohsiung, 821 Taiwan, R.O.C.

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**2010 Business Portfolio**

- **Probe Card**: 66.7% 62.1%
- **Leda**: 38.5% 31.0%
- **Solar**: 65.3% 62.4%
- **Graph** showing percentage of various business categories.
2 in 1 Machine (Prober + Sorter)

Specifications

- **Dimension**
  - Wide: 1400mm
  - Height: 1650mm (not including signal-tower)
  - Length: 1530mm
  - Weight: 1000Kg
- **Loader**
  - Wafer Cassette: 2 (8 rings for GR6/GR5)
  - Bin Cassette: 6 (25 bins with a single Cassette)
- **Wafer Size**
  - Max 6" (150mm) after expansion (for GR6/GR5)
- **Bin Area**
  - 60mm x 60mm
- **Pattern Recognition System**
  - PR System: 256 grey levels
  - Resolution: 640 pixels x 480 pixels
  - Accuracy: ± 0.025 mil (Die size 64mil x 48mil)
  - Angle Range: ± 15°

- **Reduce spacing demand for capex**
- **Reduce workforce**
- **Process improvement**
**Auto Sorting Machines**

**PT-380 SORTING**

**Specifications**
- Applicable device: Chip type LED
- Loader: Parts feeder
- Number of test station: 1 (2 option)
- Test method: Side or top surface contact
- Cycle time: Max 0.15 sec/pcs (UPH24K)
  (Including 90msec test time)
- Number of bin: 256 bulk bins
- Vacuum source: Vacuum pump
- Size: W1,160 x H1,458 x D788(mm)

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**Auto Taping Machine**

**PT-350 TAPEING**

**Specifications**
- Applicable device: Each chip type devices
- Embossed Carrier tape width: 8 (mm)
- Supply reel/ Accept reel: Max ø700/ Max. ø330
- Loader: Parts feeder with hopper
- Seal method: Heat press reciprocating method
- Cycle time: 0.09 sec/pcs (696pcs/min)
- Vacuum source: Vacuum pump
- Vision: Vision Align and check device
- Size: W870 x H1,352 x D681(mm)
LED Turnkey Solution for Probing and Sorting in Chip level and package level

Chip Level
- Prober
- Sorter

Package Level
- Handler
- Tapping

2 in 1 (Prober + Sorter)
- Reduce spacing demand for capex
- Reduce workforce
- Process improvement

Equipment Shipment

<table>
<thead>
<tr>
<th>Month</th>
<th>Units 2015</th>
<th>Units 2016</th>
<th>Growth</th>
</tr>
</thead>
<tbody>
<tr>
<td>Jan.</td>
<td>118</td>
<td>165</td>
<td>380%</td>
</tr>
<tr>
<td>Feb.</td>
<td>68</td>
<td>246</td>
<td></td>
</tr>
<tr>
<td>Mar.</td>
<td>165</td>
<td>231</td>
<td></td>
</tr>
<tr>
<td>Apr.</td>
<td>197</td>
<td>252</td>
<td></td>
</tr>
<tr>
<td>May</td>
<td>221</td>
<td>312</td>
<td></td>
</tr>
<tr>
<td>Jun.</td>
<td>274</td>
<td>192</td>
<td>-27%</td>
</tr>
<tr>
<td>Jul</td>
<td>217</td>
<td>217</td>
<td>0%</td>
</tr>
</tbody>
</table>

% Growth - 0% to 300%
**Geography & Product Mix**

**by Geography**

- **Korea, 148, 6%**
- **China, 1300, 52%**
- **Taiwan, 1063, 2%**

**by Product**

<table>
<thead>
<tr>
<th>Quarter</th>
<th>Q1-10(S)</th>
<th>Q2-10(S)</th>
<th>Q3-10(S)</th>
<th>Q4-10(S)</th>
</tr>
</thead>
<tbody>
<tr>
<td>2010</td>
<td>76</td>
<td>219</td>
<td>219</td>
<td>112</td>
</tr>
<tr>
<td>2011</td>
<td>203</td>
<td>465</td>
<td>499</td>
<td>571</td>
</tr>
</tbody>
</table>

**Growth Driver – Tablet**

**Figure-1 2010-2013 worldwide Tablet forecast**

- **Unit M**
  - **2010E**
  - **2011F**
  - **2012F**
  - **2013F**

Source: TrendForce, Dec. 2010
**Growth Driver – Monitor, NB and TV**

2011 LED Penetration Rate by Quarter

<table>
<thead>
<tr>
<th>Application</th>
<th>Panel</th>
<th>1Q11</th>
<th>2Q11</th>
<th>3Q11</th>
<th>4Q11</th>
<th>2011</th>
</tr>
</thead>
<tbody>
<tr>
<td>Total</td>
<td></td>
<td>47,689</td>
<td>49,080</td>
<td>52,657</td>
<td>49,279</td>
<td>198,705</td>
</tr>
<tr>
<td>Monitor</td>
<td></td>
<td>14,882</td>
<td>23,582</td>
<td>36,347</td>
<td>34,546</td>
<td>109,357</td>
</tr>
<tr>
<td>LED P/R</td>
<td>31.2%</td>
<td>48.0%</td>
<td>69.0%</td>
<td>70.1%</td>
<td>55.0%</td>
<td></td>
</tr>
<tr>
<td>NB+Net</td>
<td></td>
<td>67,132</td>
<td>74,625</td>
<td>80,679</td>
<td>70,521</td>
<td>292,957</td>
</tr>
<tr>
<td>LED P/R</td>
<td>97.6%</td>
<td>98.2%</td>
<td>98.5%</td>
<td>99.1%</td>
<td>98.4%</td>
<td></td>
</tr>
<tr>
<td>Total</td>
<td></td>
<td>54,907</td>
<td>56,842</td>
<td>66,518</td>
<td>63,615</td>
<td>241,882</td>
</tr>
<tr>
<td>LED P/R</td>
<td>26.1%</td>
<td>37.6%</td>
<td>50.2%</td>
<td>55.2%</td>
<td>43.1%</td>
<td></td>
</tr>
</tbody>
</table>

Unit: Kpcs

**Growth Driver – LED lighting**

LED Lighting Is Taking Off
- The LED lighting is penetrating €70bn lighting market.
- 50% penetration rate by 2015 is projected by Philips.
- And 30% LED lamp in 2010 is projected in Japan market.

Source: LEDinside
**Growth Driver – Backlight**

Summary-LED Backlight Market

- LED Backlight Penetration Rate
- LED Backlight Market Revenue

Source: LEDinside

**MOCVD - China**

- Number of LED Chip Enterprises by Year
- Enterprise Type 1 - (75 Enterprises in Total)

Source: LEDinside
**Growth Driver: IC package**

<table>
<thead>
<tr>
<th>Year</th>
<th>2006</th>
<th>2007</th>
<th>2008</th>
<th>2009</th>
<th>2010(e)</th>
<th>2011(f)</th>
<th>2012(f)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Market</td>
<td>4,245</td>
<td>4,466</td>
<td>4,588</td>
<td>3,785</td>
<td>5,467</td>
<td>6,276</td>
<td>6,499</td>
</tr>
</tbody>
</table>

單位：百萬美元

資料來源：Gartner(2010/10)：工研院 IEK(2010/11)

全球 IC 封測產業市場值

**Growth Driver: IC package unit**

**Overall IC Package unit growth**

Overall package growth CAGR ~ 9%

Source : IEK
Thank You

http://www.mpi.com.tw